Compliant with IEC 62474/ D9.00

Compliant to IEC 61249-2-21:2003

certain "reels" may be made from PVC plastic. Microchip Technology Incorporated believes the information in this form concerning substances reheir original packing materials is true and correct to the best of its knowledge and belief, as of the completeness and accuracy of data in this form because it has been compiled based on the ranges information is often protected from disclosure as trade secrets and some information may not have rovoided only as estimates of the average weight of these parts and the average weight of anticipat dopants, metals, and non-metal materials contained within silicon devices (silicon IC) in the finished Microchip Technology Incorporated and warranty, express or implied, with respect warranties provided by Microchip Technology Incorporated and its subsidiaries are contained in Miguotations, sales order acknowledgement, and invoices. Microchip disclaims any duty to notify users of updates or changes to Material Content Declaration otherwise, suffered by users or third parties as a result of the users' reliance on the information in this Certificate of Compliance for semiconductor products. Assembled package referenced above is EU REACH compliant based on the latest SVHC candidate	"Contained In" Sub-Component Mold Compound Lead Frame Lead Frame Lead Frame Lead Frame	% Total Weight 44.427 5.924 4.773 1.776 1.776 0.325 7.018 4.184	mg/part 2.488 0.332 0.267	ppm 444,270	3.30		Package Homogeneous Materials			
Silica(Amorphous) B 7631-86-0 Silica(Amorphous) B 7631-86-0 Epoxy Resin Trade Secret Epoxy Resin Trade Secret Phenol Resin 9003-35-4 Aluminium and its compounds Trade Secret Carbon Black 1333-86-4 Copper 7440-50-8 Glass fibers 65997-17-3 Phenol, polymer 9003-36-5 Silica, chemically prepared 7631-86-9 Nickel 77440-02-0 Barite 7772-43-7 Magnesium silicate 17727-43-7 Magnesium silicate 17728-6-6 Araldite GY 250 25068-38-6 (2-Methoxymethylethoxy)propanol 34590-94-8 Misc. system Aluminum-hydroxide-oxide 24623-77-6 Gold 7440-57-5 Gilver 74	Mold Compound Lead Frame Lead Frame Lead Frame Lead Frame Lead Frame	44.427 5.924 4.773 1.776 1.776 0.325 7.018	2.488 0.332 0.267			(mg) Total	Mold Compound	% ot Total Weight	59.00	
Silica(Amorphous) B Epoxy Resin Trade Secret Phenol Resin Phenol Resin Aluminium and its compounds Trade Secret Carbon Black Carbon Black Carbon Black Carbon Black Glass fibers Glass fibers Gs997-17-3 Phenol, polymer Phenol Resin Phenol R	Mold Compound Mold Compound Mold Compound Mold Compound Mold Compound Lead Frame Lead Frame Lead Frame Lead Frame Lead Frame	5.924 4.773 1.776 1.776 0.325 7.018	0.332 0.267			Silica(Amorphous) A	60676-86-0	75.30		
Epoxy Resin Phenol Resin 9003-35-4 Aluminium and its compounds Trade Secret Carbon Black 1333-66-4 Copper 7440-50-8 Glass fibers 65997-17-3 Phenol, polymer 9003-36-5 Silica, chemically prepared 7531-86-9 Nickel 7727-43-7 Magnesium silicate Araldite GY 250 Barite 7727-43-7 Magnesium silicate Araldite GY 250 2508-38-6 Araldite GY	Mold Compound Mold Compound Mold Compound Mold Compound Lead Frame Lead Frame Lead Frame Lead Frame Lead Frame	4.773 1.776 1.776 0.325 7.018	0.267	59,236		Silica(Amorphous) B	7631-86-9	10.04	l	
Phenol Resin Aluminium and its compounds Trade Secret Carbon Black Carbon Black Carbon Black Capper Tr440-50-8 Class fibers Glass fibers Glass fibers Glass fibers Ges997-17-3 Phenol, polymer Glass fibers Ges997-17-3 Phenol, polymer Ges97-17-3 Phenol, polymer Ges97-17-3 Nickel Tr440-02-0 Barite Tr440-02-0 Barite Tr440-02-0 Barite Tr440-02-0 Barite Tr440-02-0 Magnesium silicate 14807-96-6 Araldite GY 250 25068-38-6 (2-Methoxymethylethoxylpropanol 3459-94-8 Misc. System Aluminium-hydroxide-oxide Aluminium-hydroxide-oxide Gold Tr440-57-5 Siliver Tr440-22-4 Epoxy Resin Trade Secret SiO2 Filler Trade Secret Floory Resin Trade Secret Acrylic Copolymer Phenol Resin Trade Secret Phenol Resin Trade Secret Doped Silicon Tr440-21-3 Doped Gold Tr440-57-5 Doped Gold Tr440-5	Mold Compound Mold Compound Mold Compound Lead Frame Lead Frame Lead Frame Lead Frame Lead Frame	1.776 0.325 7.018	-	47,731		Epoxy Resin	Trade Secret	8.09	l	
Carbon Black Copper T7440-50-8 Glass fibers Glass fibers Fhenol, polymer 9003-36-5 Silica, chemically prepared T743-78-8-9 Nickel T7440-02-0 Barite T727-43-7 Magnesium silicate 14807-96-6 Araldite GY 250 Aluminium-hydroxide-oxide Aluminium-hydroxide-oxide T740-02-0 Silver T740-02-0 Aluminium-hydroxide-oxide Aluminium-hydroxide-oxide Aluminium-hydroxide-oxide T740-02-0 Silver T740-02-0 Silver T740-02-0 T740-03-7-6 Gold T740-03-7-6 Silver T740-22-4 Epoxy Resin Trade Secret Epoxy Resin Trade Secret Fepoxy Resin Trade Secret Fepoxy Resin Trade Secret Acrylic Copolymer Trade Secret Phenol Resin Doped Silicon T7440-21-3 Doped Gold T7440-57-5 Copper T7440-57-5 Doped Gold T7440-57-5 Au Doped Gold T7440-57-5 Copper T7440-50-8 Ni T7440-02-0 Au T7440-57-5 Copper Trade Secret Doped Gold T7440-57-5 Copper T7440-50-8 Ni T7440-02-0 Au T7440-02-0 Au T7440-57-5 Copper T740-50-8 Ni T74	Mold Compound Lead Frame Lead Frame Lead Frame Lead Frame Lead Frame Lead Frame	1.776 0.325 7.018	0.099	17,759		Phenol Resin	9003-35-4	3.01	l	
Copper 7440-50-8 Glass fibers 65997-17-3 Phenol, polymer 9003-36-5 Silica, chemically prepared 7631-86-9 Nickel 7440-02-0 Barite 7727-43-7 Magnesium silicate 14807-96-6 Araldite GY 250 25068-38-6 (2-Methoxymethylethoxy)propanol 34590-94-8 Misc. system Aluminium-hydroxide-oxide 24623-77-6 Gold 7440-57-5 Siliver 7440-22-4 Epoxy Resin 17ade Secret 5poxy Resin 17ade Secret 5poxy Resin 17ade Secret 5poxy Resin 17ade Secret 5poxy Resin 17ade Secret 19poyed Silicon 7440-21-3 Doped Silicon 7440-21-3 Doped Silicon 7440-21-3 Doped Gold 7440-57-5 Copper 7440-50-8 Ni 7440-67-5 Doped Gold 7440-57-5 Doped Gold 7440-57-5 Copper 7440-50-8 Ni 7440-57-5 Doped Gold 7440-57-5 Doped Gold 7440-57-5 Doped Gold 7440-57-5 Copper 97440-50-8 Ni 7440-67-5 Copper 97440-50-8 Ni 7440-67-5 Doped Gold 7440-57-5 Copper 97440-50-8 Ni 7440-67-5 Copper 97440-50-8 Ni 7440-67-5 Doped Gold 7440-57-5 Doped Gold 7440-57	Lead Frame Lead Frame Lead Frame Lead Frame Lead Frame	7.018	0.099	17,759		Aluminium and its compounds	Trade Secret	3.01	l	
Glass fibers 65997-17-3 Phenol, polymer 9003-36-5 Silica, chemically prepared 7631-86-9 Nickel 7440-02-0 Barite 7727-43-7 Magnesium silicate 14807-96-6 Araldite GY 250 25068-38-6 (2-Methoxymethylethoxy)propanol 34590-94-8 Misc. System Aluminium-hydroxide-oxide 24623-77-6 Gold 7440-67-5 Siliver 7440-02-4 Epoxy Resin Trade secret SiO2 Filler Trade Secret Epoxy Resin Trade Secret Doped Silicon 7440-21-3 Doped Silicon 7440-21-3 Doped Gold 7440-57-5 D	Lead Frame Lead Frame Lead Frame Lead Frame		0.018	3,245		Carbon Black	1333-86-4	0.55	1	
Phenol, polymer 9003-36-5 Silica, chemically prepared 7631-36-9 Nickel 7440-02-0 Barrite 7727-43-7 Magnesium silicate 14807-96-6 Araldite GY 250 25068-33-6 (2-Methoxymethylethoxylypropanol 34590-94-8 Misc. 9ystem Aluminium-hydroxide-oxide 24623-77-6 Gold 7440-67-5 Silver 7440-67-5 Silver 7440-22-4 Epoxy Resin Trade secret Silver 7440-21-3 Doped Silicon 7440-21-3 Doped Silicon 7440-21-3 Doped Silicon 7440-21-3 Doped Silicon 7440-67-5 Doped Gold 7440-67-5 One of the secret of t	Lead Frame Lead Frame Lead Frame	4.184	0.393	70,185			Total	100.00	19.55	
Silica, Chemically prepared Nickel Ni	Lead Frame Lead Frame	4.184	0.234 0.234	41,837 41,837	1.09	(mg) Total Copper	Lead Frame 7440-50-8	% of Total Weight 35.90	19.55	
Nickel 772-43-7 Barite 772-43-7 Magnesium silicate 14807-96-6 Araldite GY 250 25068-38-6 (2-Methoxymethylethoxy)propanol 34590-94-8 Misc. system Aluminium-hydroxide-oxide 24623-77-6 Gold 7440-57-5 Silver 7440-22-4 Epoxy Resin Trade Secret SiO2 Filler Trade Secret Epoxy Resin Trade Secret SiO2 Filler Trade Secret Acrylic Copolymer Trade Secret Phenol Resin Trade Secret Doped Silicon 7440-21-3 Doped Silicon 7440-21-3 Doped Sold 7440-57-5 Doped Gold 7440-57-5 Au Doped Silicon 7440-21-3 Doped Sold 7440-57-5 Doped Sold 7440-57-5	Lead Frame	1.564	0.234	15,640		Glass fibers	65997-17-3	21.40	ı	
Bairle 7727-43-7 Magnesium silicate 14807-96-6 Araldite GY 250 25068-38-6 (2-Methoxymethylethoxy)propanol 34590-94-8 Misc. system Aluminium-hydroxide-oxide 24623-77-6 Gold 7440-57-5 Silver 7440-22-4 Epoxy Resin Trade secret SiO2 Filler Trade Secret Epoxy Resin Trade Secret Epoxy Resin Trade Secret Epoxy Resin Trade Secret Doped Silicon 7440-21-3 Doped Silicon 7440-21-3 Doped Gold 7440-57-5 Doped Gol		0.762	0.043	7,625		Phenol, polymer	9003-36-5	21.40	ı	
Araldule GY 250 (2-Methoxymethylethoxy)propanol Misc. System Aluminium-hydroxide-oxide Aluminium-hydroxide-oxide Gold 7440-57-5 Silver 7440-57-5 Silver 7440-22-4 Epoxy Resin Trade secret SiO2 Filler Trade Secret Epoxy Resin Trade Secret Flenol Resin Acrylic Copolymer Trade Secret Phenol Resin Trade Secret Phenol Resin Trade Secret Doped Silicon 7440-21-3 Doped Silicon 7440-21-3 Doped Gold 7440-57-5 Copper 7440-57-5 Copper 7440-57-5 Copper 7440-57-5 Au Trade Secret Ni 7440-02-0 Au 7440-57-5 Copper 7440-57-5 Copper 7440-57-5 Doped Solid Trade Secret Ni 7440-02-0 Au Trade Secret O.0056 g Total Dis semiconductor device and its homogenous materials comply with EU Directives: 2002/95/EC (purplication of the semiconductor device and its homogenous materials comply with EU Directives: 2002/95/EC (purplication of the semiconductor device and belief as of the date of this document, there is no credible reason to not below the threshold of regulatory concern for any regulatory scheme world-wide. Olding compounds used by Microchip meet the UL94 V0 flammability standard for plastics. You c tp://ul.com/global/eng/pages/offerings/industries/chemicals/plastics/ loring compounds used by Microchip meet the UL94 V0 flammability standard for plastics. You c tp://ul.com/global/eng/pages/offerings/industries/chemicals/plastics/ loring compounds used by Microchip meet the UL94 V0 flammability standard for plastics. You c tp://ul.com/global/eng/pages/offerings/industries/chemicals/plastics/ loring compounds used by Microchip meet the UL94 V0 flammability standard for plastics. You c tp://ul.com/global/eng/pages/offerings/industries/chemicals/plastics/ loring compounds used by Microchip meet the UL94 V0 flammability standard for plastics. You c tp://ul.com/global/eng/pages/offerings/industries/chemicals/plastics/ loring compounds used by Microchip rectives the short showed by the secret and some information may not have a protected from disclosure as trade secrets and some in	Lead Frame	0.489	0.027	4,888		Silica, chemically prepared	7631-86-9	8.00	l	
(2-Methoxymethylethoxy)propanol Miss. Miss. System Aluminium-hydroxide-oxide Aluminium-hydroxide-oxide	Lead Frame	0.391	0.022	3,910		Nickel	7440-02-0	3.90	l	
Misc. Aluminium-hydroxide-oxide Aluminium-hydroxide-oxide Cold Aluminium-hydroxide-oxide Cold Aluminium-hydroxide-oxide Cold Aluminium-hydroxide-oxide Cold Aluminium-hydroxide-oxide Cold Aluminium-hydroxide-oxide Epoxy Resin Frade secret Epoxy Resin Frade Secret Epoxy Resin Frade Secret Epoxy Resin Frade Secret Acrylic Copolymer Frade Secret Phenol Resin Frade Secret Phenol Resin Trade Secret Phenol Resin Trade Secret Doped Silicon 7440-21-3 Doped Silicon 7440-21-3 Doped Gold 7440-57-5 Copper 7440-57-5 Copper Au 7440-57-5 Ni 7440-02-0 Au 7440-57-5 O.0056 g Total Inis semiconductor device and its homogenous materials comply with EU Directives: 2002/95/EC (2015) and 2000/53/EC and 2016/774/EU (End-of-Life Vehicles (ELV) without exemption (zero) compliance with the above EU Directives has been verified via internal design controls, supplier de a chemical substance is absent from the list above, the chemical substance is NOT an intentional corporated's knowledge and belief as of the date of this document, there is no credible reason to not below the threshold of regulatory concern for any regulatory scheme world-wide. Olding compounds used by Microchip meet the UL94 V0 flammability standard for plastics. You c ttp://ul.com/global/eng/pages/offerings/industries/chemicals/plastics/ terrain "reels" may be made from PVC plastic. icrochip Technology Incorporated believes the information in this form concerning substances re original packing materials is true and correct to the best of its knowledge and belief, as of the supplements and accuracy of data in this form because it has been compiled based on the ranges formation is often protected from disclosure as trade secrets and some information may not have ovided only as estimates of the average weight of these parts and the average weight of anticipat popants, metals, and non-metal materials contained within silicon devices (silicon IC) in the finishe icrochip Technology Incorporated and its subsidiaries are containe	Lead Frame	0.391	0.022	3,910		Barite	7727-43-7	2.50	l	
Aluminium-hydroxide-oxide Gold T440-57-5 Silver Gold T440-57-5 Silver T7440-22-4 Epoxy Resin Trade secret SiO2 Filler Trade Secret Epoxy Resin Trade Secret Epoxy Resin Trade Secret Epoxy Resin Trade Secret Acrylic Copolymer Trade Secret Phenol Resin Trade Secret Phenol Resin Trade Secret Doped Silicon T7440-21-3 Doped Silicon T7440-21-3 Doped Gold T7440-57-5 Doped Gold T7440-57-5 Copper T7440-50-8 Ni T7440-62-0 Au T7440-67-5 Doped Solicon Au T7440-67-5 Copper T7440-67-5 Copper T7440-67-5 Doped Solicon Au T7440-67-5 Copper T7440-69-8 Ni T	Lead Frame	0.156	0.009	1,564		Magnesium silicate	14807-96-6	2.00	l	
Gold 7440-57-5 Silver 7440-22-4 Epoxy Resin Trade secret Acrylic Copolymer Trade Secret Phenol Resin Trade Secret Phenol Resin Trade Secret Doped Silicon 7440-21-3 Doped Silicon 7440-21-3 Doped Solicon 7440-57-5 Doped Solicon 7440-57-5 Copper 7440-50-8 Ni 7440-50-8 Ni 7440-02-0 Au 7440-57-5 O.0056 g Total Diss semiconductor device and its homogenous materials comply with EU Directives: 2002/95/EC (2015) and 2000/53/EC and 2016/774/EU (End-of-Life Vehicles (ELV) without exemption (zero) Dompliance with the above EU Directives has been verified via internal design controls, supplier de a chemical substance is absent from the list above, the chemical substance is NOT an intentional corporated's knowledge and belief as of the date of this document, there is no credible reason to not below the threshold of regulatory concern for any regulatory scheme world-wide. Olding compounds used by Microchip meet the UL94 V0 flammability standard for plastics. You c typ://ul.com/global/eng/pages/offerings/industries/chemicals/plastics/ the protective "tubes" in which the specific product is shipped are made from polyvinyl chloride (I vertain "reels" may be made from PVC plastic. Icrochip Technology Incorporated believes the information in this form concerning substances re ire original packing materials is true and correct to the best of its knowledge and belief, as of the supplemental is a true and correct to the best of its knowledge and belief, as of the supplemental is in the and correct to the best of its knowledge and belief, as of the supplemental is its of the separate and some information may not have ovided only as estimates of the average weight of these parts and the average weight of anticipal opants, metals, and non-metal materials contained within silicon devices (silicon IC) in the finishe for cohip Technology Incorporated and its subsidia	Lead Frame	0.293	0.016	2,933		Araldite GY 250	25068-38-6	2.00	j	
Silver 7440-22-4 Epoxy Resin Trade secret SiO2 Filler Trade Secret Epoxy Resin Trade Secret Epoxy Resin Trade Secret Epoxy Resin Trade Secret Acrylic Copolymer Trade Secret Phenol Resin Trade Secret Phenol Resin Trade Secret Phenol Resin Trade Secret Doped Silicon 7440-21-3 Doped Silicon 7440-21-3 Doped Gold 7440-57-5 Doped Gold 7440-57-5 Copper 7440-50-8 Ni 7440-02-0 Au 7440-57-5 O.0056 g Total his semiconductor device and its homogenous materials comply with EU Directives: 2002/95/EC (2015) and 2000/53/EC and 2016/774/EU (End-of-Life Vehicles (ELV) without exemption (zero) ompliance with the above EU Directives has been verified via internal design controls, supplier de a chemical substance is absent from the list above, the chemical substance is NOT an intentional corporated's knowledge and belief as of the date of this document, there is no credible reason to not below the threshold of regulatory concern for any regulatory scheme world-wide. olding compounds used by Microchip meet the UL94 V0 flammability standard for plastics. You can be protective "tubes" in which the specific product is shipped are made from polyvinyl chloride (I ertain "reels" may be made from PVC plastic. icrochip Technology Incorporated believes the information in this form concerning substances reir original packing materials is true and correct to the best of its knowledge and belief, as of the protective "tubes" in which the specific product is shipped are made from polyvinyl chloride (I ertain "reels" may be made from PVC plastic. icrochip Technology Incorporated does not provide any warranty, express or implied, with respector provided only as estimates of the average weight of these parts and the average weight of anticipat oppants, metals, and non-metal materials contained within silicon devices (silicon IC) in the finishe icrochip Technology Incorporated and its subsidiaries are contained in Muotations, sales order acknowledgement, and invoices.	Lead Frame	0.098	0.005	978		(2-Methoxymethylethoxy)propanol	34590-94-8	0.80	j	
Epoxy Resin SiO2 Filler Trade Secret Epoxy Resin Trade Secret Epoxy Resin Trade Secret Acrylic Copolymer Trade Secret Phenol Resin Trade Secret Phenol Resin Trade Secret Doped Silicon 7440-21-3 Doped Silicon 7440-21-3 Doped Gold 7440-57-5 Doped Gold 7440-57-5 Copper 7440-50-8 Ni 7440-50-8 Ni 7440-57-5 Au 7440-57-5 Ni 0.0056 g Total T	Lead Frame	0.020	0.001	196		Misc.	system 24623-77-6	1.50 0.50	l	
SiO2 Filler Epoxy Resin Trade Secret Acrylic Copolymer Trade Secret Phenol Resin Trade Secret Doped Sillicon 7440-21-3 Doped Sillicon 7440-21-3 Doped Sillicon 7440-57-5 Doped Sillicon 7440-57-5 Doped Sold 7440-57-5 Copper 7440-57-5 Copper 7440-57-5 Ni 7440-02-0 Au 74	Die Attach 1 Die Attach 1	0.675 0.075	0.038	6,750 750		Aluminium-hydroxide-oxide Gold	7440-57-5	0.10	j	
Epoxy Resin Trade Secret Acrylic Copolymer Trade Secret Phenol Resin Trade Secret Phenol Resin Trade Secret Doped Silicon 7440-21-3 Doped Silicon 7440-21-3 Doped Silicon 7440-21-3 Doped Gold 7440-57-5 Copper 7440-50-8 Ni 7440-57-5 Au 7440-57-5 Doped Gold 7440-57-5 Au 7440-57-5 Doped Gold 7440-57-5 Au 7440-57-5 Doped Gold 7440-57-5 Au 7440-50-8 Au 7440-57-5 Doped Gold 7440-57-5 Doped Gold 7440-50-8 Au 7440-57-5 Doped Gold 7440-50-8 Au 7440-50-8 Doped Gold 7440-50-8 Doped Gold 7440-50-8 Doped Gold 7440-50-8 Ni 7440-50-8 Doped Gold 7440-50-8 Ni 7440-50-8 Doped Gold 7440-50-8 Ni 7440-50-8 Doped Gold 740-50-8 Doped Gold 7440-50-8 Doped Gold	Die Attach 2	0.075	0.004	7,723		Gold	Total	100.00	i	
Acrylic Copolymer Phenol Resin Trade Secret Phenol Resin Trade Secret Doped Silicon 7440-21-3 Doped Silicon 7440-21-3 Doped Silicon 7440-21-3 Doped Silicon 7440-57-5 Doped Gold 7440-57-5 Doped Gold 7440-57-5 Doped Gold 7440-57-5 Doped Gold 7440-50-8 Ni 7440-50-8 Ni 7440-50-8 Ni 7440-57-5 O.0056 g Total Nis semiconductor device and its homogenous materials comply with EU Directives: 2002/95/EC (2015) and 2000/53/EC and 2016/774/EU (End-of-Life Vehicles (ELV) without exemption (zero) ompliance with the above EU Directives has been verified via internal design controls, supplier de a chemical substance is absent from the list above, the chemical substance is NOT an intentional corporated's knowledge and belief as of the date of this document, there is no credible reason to not below the threshold of regulatory concern for any regulatory scheme world-wide. Olding compounds used by Microchip meet the UL94 V0 flammability standard for plastics. You city://ul.com/global/eng/pages/offerings/industries/chemicals/plastics/ the protective "tubes" in which the specific product is shipped are made from polyvinyl chloride (I bertain "reels" may be made from PVC plastic. icrochip Technology Incorporated believes the information in this form concerning substances re ire original packing materials is true and correct to the best of its knowledge and belief, as of the ompleteness and accuracy of data in this form because it has been compiled based on the ranges formation is often protected from disclosure as trade secrets and some information may not have voivided only as estimates of the average weight of these parts and the average weight of anticipat oppants, metals, and non-metal materials contained within silicon devices (silicon IC) in the finishe icrochip Technology Incorporated does not provide any warranty, express or implied, with respect arranties provided by Microchip Technology Incorporated and its subsidiaries are contained in Microchip Technology Incorporated and its subsidiaries are contained in Microchip Techno	Die Attach 2	0.390	0.043	3,899	0.04	(mg) Total	Die Attach 1	% of Total Weight	0.75	
Phenol Resin Trade Secret Doped Silicon 7440-21-3 Doped Silicon 7440-21-3 Doped Gold 7440-57-5 Doped Gold 7440-57-5 Copper 7440-50-8 Ni 7440-02-0 Au 7440-67-5 Au 7440-67-5 Au 7440-67-5 O.0056 g Total his semiconductor device and its homogenous materials comply with EU Directives: 2002/95/EC (2015) and 2000/53/EC and 2016/77/EU (End-of-Life Vehicles (ELV) without exemption (zero) ompliance with the above EU Directives has been verified via internal design controls, supplier de a chemical substance is NOT an intentional acorporated's knowledge and belief as of the date of this document, there is no credible reason to a not below the threshold of regulatory concern for any regulatory scheme world-wide. Iolding compounds used by Microchip meet the UL94 V0 flammability standard for plastics. You can be protective "tubes" in which the specific product is shipped are made from polyvinyl chloride (I ertain "reels" may be made from PVC plastic. Licrochip Technology Incorporated believes the information in this form concerning substances reir original packing materials is true and correct to the best of its knowledge and belief, as of the ompleteness and accuracy of data in this form because it has been compiled based on the ranges formation is often protected from disclosure as trade secrets and some information may not have rovided only as estimates of the average weight of these parts and the average weight of anticipat oppants, metals, and non-metal materials contained within silicon devices (silicon IC) in the finishe icrochip Technology Incorporated does not provide any warranty, express or implied, with respect arranties provided by Microchip Technology Incorporated and its subsidiaries are contained in Muotations, sales order acknowledgement, and invoices.	Die Attach 2	0.234	0.013	2,339	0.04	Silver	7440-22-4	90.00	0.75	
Doped Silicon 7440-21-3 Doped Gold 7440-21-3 Doped Gold 7440-57-5 Doped	Die Attach 2	0.234	0.013	2,339		Epoxy Resin	Trade secret	10.00	j	
Doped Silicon 7440-21-3 Doped Gold 7440-57-5 Doped Gold 7440-57-5 Doped Gold 7440-57-5 Doped Gold 7440-57-5 Copper 7440-50-8 Ni 7440-02-0 Au 7440-57-5 O.0056 g Total his semiconductor device and its homogenous materials comply with EU Directives: 2002/95/EC (015) and 2000/53/EC and 2016/774/EU (End-of-Life Vehicles (ELV) without exemption (zero) compliance with the above EU Directives has been verified via internal design controls, supplier de a chemical substance is absent from the list above, the chemical substance is NOT an intentional noorporated's knowledge and belief as of the date of this document, there is no credible reason to s not below the threshold of regulatory concern for any regulatory scheme world-wide. Holding compounds used by Microchip meet the UL94 V0 flammability standard for plastics. You c ttp://ul.com/global/eng/pages/offerings/industries/chemicals/plastics/ hierochip Technology Incorporated believes the information in this form concerning substances reteir original packing materials is true and correct to the best of its knowledge and belief, as of the ompleteness and accuracy of data in this form because it has been compiled based on the ranges formation is often protected from disclosure as trade secrets and some information may not have rovided only as estimates of the average weight of these parts and the average weight of anticipat lopants, metals, and non-metal materials contained within silicon devices (silicon IC) in the finished in the control of the second of the subsidiaries are contained in Muctations, sales order acknowledgement, and invoices. Ilicrochip disclaims any duty to notify users of updates or changes to Material Content Declaration therwise, suffered by users or third parties as a result of the users' reliance on the information in his Certificate of Compliance for semiconductor products.	Chip (Die) 1	3.810	0.213	38,100			Total	100.00	•	
Doped Gold 7440-57-5 Doped Gold 7440-57-5 Doped Gold 7440-57-5 Copper 7440-50-8 Ni 7440-50-8 Ni 7440-50-8 Ni 7440-50-8 Ni 7440-57-5 Doubled Gold 7440-57-5 Au 7440-57-5 Doubled Gold 7440-57-5 Au 7440-57-5 Doubled Gold 7440-57-5 Doubled Gold 7440-57-5 Doubled Gold 7440-57-5 Doubled Gold Total his semiconductor device and its homogenous materials comply with EU Directives: 2002/95/EC (2015) and 2000/53/EC and 2016/774/EU (End-of-Life Vehicles (ELV) without exemption (zero) ompliance with the above EU Directives has been verified via internal design controls, supplier de a chemical substance is absent from the list above, the chemical substance is NOT an intentional ocroproated's knowledge and belief as of the date of this document, there is no credible reason to not below the threshold of regulatory concern for any regulatory scheme world-wide. Odding compounds used by Microchip meet the UL94 V0 flammability standard for plastics. You of ttp://lu.com/global/eng/pages/offerings/industries/chemicals/plastics/ idirective "tubes" in which the specific product is shipped are made from polyvinyl chloride (I ertain "reels" may be made from PVC plastic. icrochip Technology Incorporated believes the information in this form because it has been compiled based on the ranges formation is often protected from disclosure as trade secrets and some information may not have rovided only as estimates of the average weight of these parts and the average weight of anticipat pants, metals, and non-metal materials contained within silicon devices (silicon IC) in the finishe icrochip Technology Incorporated does not provide any warranty, express or implied, with respect arranties provided by Microchip Technology Incorporated and its subsidiaries are contained in Muotations, sales order acknowledgement, and invoices. icrochip disclaims any duty to notify users of updates or changes to Material Content Declaration therwise, suffered by users or third parties as a result of the users' reliance on the information in isic Certificate	Chip (Die) 2	1.700	0.095	17,000	0.09	(mg) Total	Die Attach 2	% of Total Weight	1.63	
Doped Gold 7440-57-5 Copper 7440-50-8 Ni 7440-50-8 Ni 7440-50-8 Au 7440-57-5 0.0056 g Total his semiconductor device and its homogenous materials comply with EU Directives: 2002/95/EC (015) and 2000/53/EC and 2016/774/EU (End-of-Life Vehicles (ELV) without exemption (zero) compliance with the above EU Directives has been verified via internal design controls, supplier de a chemical substance is absent from the list above, the chemical substance is NOT an intentional accorporated's knowledge and belief as of the date of this document, there is no credible reason to is not below the threshold of regulatory concern for any regulatory scheme world-wide. Iolding compounds used by Microchip meet the UL94 V0 flammability standard for plastics. You cetter: "tubes" in which the specific product is shipped are made from polyvinyl chloride (I ertain "reels" may be made from PVC plastic. Ilicrochip Technology Incorporated believes the information in this form concerning substances re incir original packing materials is true and correct to the best of its knowledge and belief, as of the ompleteness and accuracy of data in this form because it has been compiled based on the ranges information is often protected from disclosure as trade secrets and some information may not have rovided only as estimates of the average weight of these parts and the average weight of anticipat opants, metals, and non-metal materials contained within silicon devices (silicon IC) in the finishe licrochip Technology Incorporated and its subsidiaries are contained in Muotations, sales order acknowledgement, and invoices. Ilicrochip disclaims any duty to notify users of updates or changes to Material Content Declaration therwise, suffered by users or third parties as a result of the users' reliance on the information in his Certificate of Compliance for semiconductor products.	Wire Bond 1	0.650	0.036	6,500		SiO2 Filler	Trade Secret	47.38		
Ni 7440-02-0 Au 7440-57-5 O.0056 g Total his semiconductor device and its homogenous materials comply with EU Directives: 2002/95/EC (: 015) and 2000/53/EC and 2016/774/EU (End-of-Life Vehicles (ELV) without exemption (zero) compliance with the above EU Directives has been verified via internal design controls, supplier de a chemical substance is absent from the list above, the chemical substance is NOT an intentional accrporated's knowledge and belief as of the date of this document, there is no credible reason to is not below the threshold of regulatory concern for any regulatory scheme world-wide. Iolding compounds used by Microchip meet the UL94 V0 flammability standard for plastics. You c ttp://ul.com/global/eng/pages/offerings/industries/chemicals/plastics/ he protective "tubes" in which the specific product is shipped are made from polyvinyl chloride (I ertain "reels" may be made from PVC plastic. Ilicrochip Technology Incorporated believes the information in this form concerning substances re erio original packing materials is true and correct to the best of its knowledge and belief, as of the ompleteness and accuracy of data in this form because it has been compiled based on the ranges flormation is often protected from disclosure as trade secrets and some information may not have rovided only as estimates of the average weight of these parts and the average weight of anticipat opants, metals, and non-metal materials contained within silicon devices (silicon IC) in the finishe licrochip Technology Incorporated does not provide any warranty, express or implied, with respectarranties provided by Microchip Technology Incorporated and its subsidiaries are contained in Muotations, sales order acknowledgement, and invoices. licrochip disclaims any duty to notify users of updates or changes to Material Content Declaration therwise, suffered by users or third parties as a result of the users' reliance on the information in nis Certificate of Compliance for semiconductor products.	Wire Bond 2	0.150	0.008	1,500		Epoxy Resin	Trade Secret	23.92	l	
Au 7440-57-5 0.0056 g Total hits semiconductor device and its homogenous materials comply with EU Directives: 2002/95/EC (0.015) and 2000/53/EC and 2016/774/EU (End-of-Life Vehicles (ELV) without exemption (zero) ompliance with the above EU Directives has been verified via internal design controls, supplier de a chemical substance is absent from the list above, the chemical substance is NOT an intentional corporated's knowledge and belief as of the date of this document, there is no credible reason to a not below the threshold of regulatory concern for any regulatory scheme world-wide. Iolding compounds used by Microchip meet the UL94 V0 flammability standard for plastics. You ce ttp://ul.com/global/eng/pages/offerings/industries/chemicals/plastics/ he protective "tubes" in which the specific product is shipped are made from polyvinyl chloride (I ertain "reels" may be made from PVC plastic. Icrochip Technology Incorporated believes the information in this form concerning substances re eiro riginal packing materials is true and correct to the best of its knowledge and belief, as of the ompleteness and accuracy of data in this form because it has been complied based on the ranges formation is often protected from disclosure as trade secrets and some information may not have rovided only as estimates of the average weight of these parts and the average weight of anticipat popants, metals, and non-metal materials contained within silicon devices (silicon IC) in the finishe iicrochip Technology Incorporated does not provide any warranty, express or implied, with respect arranties provided by Microchip Technology Incorporated and its subsidiaries are contained in Muotations, sales order acknowledgement, and invoices. iicrochip disclaims any duty to notify users of updates or changes to Material Content Declaration therwise, suffered by users or third parties as a result of the users' reliance on the information in iis Certificate of Compliance for semiconductor products.	Plating on external leads (pins)	12.250	0.686	122,496		Acrylic Copolymer	Trade Secret	14.35	l	
O.0056 g Total nis semiconductor device and its homogenous materials comply with EU Directives: 2002/95/EC (2015) and 2000/53/EC and 2016/774/EU (End-of-Life Vehicles (ELV) without exemption (zero) ompliance with the above EU Directives has been verified via internal design controls, supplier de a chemical substance is absent from the list above, the chemical substance is NOT an intentional corporated's knowledge and belief as of the date of this document, there is no credible reason to not below the threshold of regulatory concern for any regulatory scheme world-wide. olding compounds used by Microchip meet the UL94 V0 flammability standard for plastics. You c tp://ul.com/global/eng/pages/offerings/industries/chemicals/plastics/ icrochip Technology Incorporated believes the information in this form polyvinyl chloride (I ertain "reels" may be made from PVC plastic. icrochip Technology Incorporated believes the information in this form concerning substances re eir original packing materials is true and correct to the best of its knowledge and belief, as of the morpleteness and accuracy of data in this form because it has been compiled based on the ranges formation is often protected from disclosure as trade secrets and some information may not have voided only as estimates of the average weight of these parts and the average weight of anticipat popants, metals, and non-metal materials contained within silicon devices (silicon IC) in the finishe icrochip Technology Incorporated does not provide any warranty, express or implied, with respect arranties provided by Microchip Technology Incorporated and its subsidiaries are contained in M joutations, sales order acknowledgement, and invoices. icrochip disclaims any duty to notify users of updates or changes to Material Content Declaration therwise, suffered by users or third parties as a result of the users' reliance on the information in is Certificate of Compliance for semiconductor products.	Plating on external leads (pins)	0.383	0.021	3,828		Phenol Resin	Trade Secret	14.35	1	
his semiconductor device and its homogenous materials comply with EU Directives: 2002/95/EC (; 015) and 2000/53/EC and 2016/77/EU (End-of-Life Vehicles (ELV) without exemption (zero) ompliance with the above EU Directives has been verified via internal design controls, supplier do a chemical substance is absent from the list above, the chemical substance is NOT an intentional corporated's knowledge and belief as of the date of this document, there is no credible reason to not below the threshold of regulatory concern for any regulatory scheme world-wide. olding compounds used by Microchip meet the UL94 V0 flammability standard for plastics. You of the protective "tubes" in which the specific product is shipped are made from polyvinyl chloride (I ertain "reels" may be made from PVC plastic. icrochip Technology Incorporated believes the information in this form concerning substances reir original packing materials is true and correct to the best of its knowledge and belief, as of the ompleteness and accuracy of data in this form because it has been compiled based on the ranges formation is often protected from disclosure as trade secrets and some information may not have rovided only as estimates of the average weight of these parts and the average weight of anticipat oppants, metals, and non-metal materials contained within silicon devices (silicon IC) in the finishe icrochip Technology Incorporated does not provide any warranty, express or implied, with respect arranties provided by Microchip Technology Incorporated and its subsidiaries are contained in Muotations, sales order acknowledgement, and involoces. icrochip disclaims any duty to notify users of updates or changes to Material Content Declaration therwise, suffered by users or third parties as a result of the users' reliance on the information in its Certificate of Compliance for semiconductor products.	Plating on external leads (pins)	0.128	0.007	1,276			Total	100.00		
his semiconductor device and its homogenous materials comply with EU Directives: 2002/95/EC (conf) and 2000/53/EC and 2016/774/EU (End-of-Life Vehicles (ELV) without exemption (zero) ompliance with the above EU Directives has been verified via internal design controls, supplier do a chemical substance is absent from the list above, the chemical substance is NOT an intentional accorporated's knowledge and belief as of the date of this document, there is no credible reason to a not below the threshold of regulatory concern for any regulatory scheme world-wide. Iolding compounds used by Microchip meet the UL94 V0 flammability standard for plastics. You of the protective "tubes" in which the specific product is shipped are made from polyvinyl chloride (I pertain "reels" may be made from PVC plastic. Icrochip Technology Incorporated believes the information in this form concerning substances reir original packing materials is true and correct to the best of its knowledge and belief, as of the ompleteness and accuracy of data in this form because it has been compiled based on the ranges information is often protected from disclosure as trade secrets and some information may not have rovided only as estimates of the average weight of these parts and the average weight of these parts and the average weight of anticipat oppants, metals, and non-metal materials contained within silicon devices (silicon IC) in the finishe iicrochip Technology Incorporated does not provide any warranty, express or implied, with respect arranties provided by Microchip Technology Incorporated and its subsidiaries are contained in Muotations, sales order acknowledgement, and incorporate and its subsidiaries are contained in Muotations, sales order acknowledgement, and incorporate and its subsidiaries are contained in Muotations, sales order acknowledgement, and incorporate and its subsidiaries are contained in Muotations, sales order acknowledgement, and incorporate order orderation therwise, suffered by users or third parties as a result o	TOTALS	100.000	5.600	1,000,000	0.21	Total (mg)	Chip (Die) 1 7440-21-3	% of Total Weight 100.00	3.81	
corporated's knowledge and belief as of the date of this document, there is no credible reason to not below the threshold of regulatory concern for any regulatory scheme world-wide. Delding compounds used by Microchip meet the UL94 V0 flammability standard for plastics. You captivally compounds used by Microchip meet the UL94 V0 flammability standard for plastics. You captivally cap	,	ouno 2011, una	20.0,000,20 (o i	0.10	Total (mg)	Chip (Die) 2	% of Total Weight	1.70	
tp://ul.com/global/eng/pages/offerings/industries/chemicals/plastics/ he protective "tubes" in which the specific product is shipped are made from polyvinyl chloride (I ratian "reels" may be made from PVC plastic. hicrochip Technology Incorporated believes the information in this form concerning substances re eir original packing materials is true and correct to the best of its knowledge and belief, as of the mpleteness and accuracy of data in this form because it has been compiled based on the ranges formation is often protected from disclosure as trade secrets and some information may not have ovided only as estimates of the average weight of these parts and the average weight of anticipal opants, metals, and non-metal materials contained within silicon devices (silicon IC) in the finishe icrochip Technology Incorporated does not provide any warranty, express or implied, with respect arranties provided by Microchip Technology Incorporated and its subsidiaries are contained in M totations, sales order acknowledgement, and invoices. icrochip disclaims any duty to notify users of updates or changes to Material Content Declaration herwise, suffered by users or third parties as a result of the users' reliance on the information in is Certificate of Compliance for semiconductor products.	ingredient in the semiconductor device and, believe that the unavoidable impurity concer	to the best of M tration of the ch	icrochip Tech emical substa	nology ince, if any,		Doped Silicon	7440-21-3	100.00		
retain "reels" may be made from PVC plastic. crochip Technology Incorporated believes the information in this form concerning substances re ir original packing materials is true and correct to the best of its knowledge and belief, as of the impleteness and accuracy of data in this form because it has been compiled based on the ranges formation is often protected from disclosure as trade secrets and some information may not have ovided only as estimates of the average weight of these parts and the average weight of anticipat opants, metals, and non-metal materials contained within silicon devices (silicon IC) in the finished crochip Technology Incorporated does not provide any warranty, express or implied, with respect arranties provided by Microchip Technology Incorporated and its subsidiaries are contained in Miotations, sales order acknowledgement, and invoices. crochip disclaims any duty to notify users of updates or changes to Material Content Declaration herwise, suffered by users or third parties as a result of the users' reliance on the information in is Certificate of Compliance for semiconductor products.	•						Total	100.00		
eir original packing materials is true and correct to the best of its knowledge and belief, as of the impleteness and accuracy of data in this form because it has been compiled based on the ranges formation is often protected from disclosure as trade secrets and some information may not have ovided only as estimates of the average weight of these parts and the average weight of anticipat ppants, metals, and non-metal materials contained within silicon devices (silicon IC) in the finishe icrochip Technology Incorporated does not provide any warranty, express or implied, with respect arranties provided by Microchip Technology Incorporated and its subsidiaries are contained in M iotations, sales order acknowledgement, and invoices. icrochip disclaims any duty to notify users of updates or changes to Material Content Declaration herwise, suffered by users or third parties as a result of the users' reliance on the information in is Certificate of Compliance for semiconductor products. ssembled package referenced above is EU REACH compliant based on the latest SVHC candidate	The protective "tubes" in which the specific product is shipped are made from polyvinyl chloride (PVC) plastic. "Window envelopes" used to hold the packing slip on the outer box and certain "reels" may be made from PVC plastic.					(mg) Total	Wire Bond 1	% of Total Weight	0.65	
rarranties provided by Microchip Technology Incorporated and its subsidiaries are contained in M uotations, sales order acknowledgement, and invoices. licrochip disclaims any duty to notify users of updates or changes to Material Content Declaration therwise, suffered by users or third parties as a result of the users' reliance on the information in is Certificate of Compliance for semiconductor products. ssembled package referenced above is EU REACH compliant based on the latest SVHC candidate	Microchip Technology Incorporated believes the information in this form concerning substances restricted by RoHS in Microchip Technology Incorporated's semiconductor devices in heir original packing materials is true and correct to the best of its knowledge and belief, as of the date listed in this form. Microchip Technology Incorporated cannot guarantee the completeness and accuracy of data in this form because it has been compiled based on the ranges provided in Material Safety Data Sheets provided by raw material suppliers. Supplier information is often protected from disclosure as trade secrets and some information may not have been provided by subcontract assemblers and raw material suppliers. Information is orvided only as estimates of the average weight of and the average weight of and the average weight of an and the average weight of an another accordance of the average weight of an another accordance of the average weight of an another accordance of the average weight of an accordance of the average weight of a contract of the					Doped Gold	7440-57-5	100.00		
therwise, suffered by users or third parties as a result of the users' reliance on the information in nis Certificate of Compliance for semiconductor products. ssembled package referenced above is EU REACH compliant based on the latest SVHC candidate.							Total	100.00		
		· · · · · · · · · · · · · · · · · · ·					Wire Bond 2	% of Total Weight	0.15	
tp://echa.europa.eu/web/guest/candidate-list-table	Material Content Declarations (MCD) or indep					Doped Gold	7440-57-5	100.00	I	
	Material Content Declarations (MCD) or indep						Total Plating on external	100.00		
	Material Content Declarations (MCD) or indep				0.71	(mg) Total	leads (pins)	% of Total Weight	12.76	
	Material Content Declarations (MCD) or indep				***	0		96.00	l	
	Material Content Declarations (MCD) or indep				****	Copper	7440-50-8			
	Material Content Declarations (MCD) or indep					Copper Ni Au	7440-50-8 7440-02-0 7440-57-5	3.00 1.00	1	

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